CLAIMS:

What is claimed is:

1. A focus ring assembly comprising:

a focus ring; and

a secondary focus ring coupled to said focus ring, wherein said focus ring is configured to couple to a substrate holder configured to support a substrate exposed to a process in a processing system, and said secondary focus ring is configured to reduce deposition of material from said process on a backside surface of said substrate.

2. The substrate holder as recited in claim 1, wherein said secondary focus ring comprises a compliant material.

3. The substrate holder as recited in claim 2, wherein said compliant material comprises at least one of silicone rubber, polyimide, and Teflon.

4. The substrate holder as recited in claim 1, wherein said secondary focus ring comprises a rigid material.

5. The substrate holder as recited in claim 4, wherein said rigid material comprises at least one of a ceramic material, silicon, silicon carbide, silicon nitride, silicon dioxide, carbon, sapphire, and alumina.

6. The substrate holder as recited in claim 1, wherein said secondary focus ring comprises silicon having a resistivity less than or equal to 1 Ω-cm.

7. The substrate holder as recited in claim 1, wherein a clearance space is formed between said substrate and said focus ring, and said clearance space exposes at least a portion of said backside surface on said substrate and said secondary focus ring reduces said clearance space.

8. The substrate holder as recited in claim 7, wherein said secondary focus ring reduces exposure of said backside surface.

9. The substrate holder as recited in claim 1, wherein a portion of said backside surface on said substrate is exposed and wherein said secondary focus ring reduces said exposure of said backside surface.

10. The substrate holder as recited in claim 1, wherein said secondary focus ring makes contact with said substrate and makes contact with said focus ring.

11. A method of using a focus ring assembly for surrounding a substrate upon a substrate holder in a processing system comprising:

installing said focus ring assembly in said processing system, wherein said focus ring assembly comprises a focus ring coupled to said substrate holder, and a secondary focus ring coupled to said focus ring and configured to reduce deposition of material from said process on a backside surface of said substrate;

loading said substrate into said processing system; and

processing said substrate.

12. The method as recited in claim 11, wherein said secondary focus ring comprises a compliant material.

13. The method as recited in claim 12, wherein said compliant material comprises at least one of silicone rubber, polyimide, and Teflon.

14. The method as recited in claim 11, wherein said secondary focus ring comprises a rigid material.

15. The method as recited in claim 14, wherein said rigid material comprises at least one of a ceramic material, silicon, silicon carbide, silicon nitride, silicon dioxide, carbon, sapphire, and alumina.

16. The method as recited in claim 11, wherein said secondary focus ring comprises silicon having a resistivity less than or equal to 1 Ω-cm.

17. The method as recited in claim 11, wherein a clearance space is formed between said substrate and said focus ring, and said clearance space exposes at least a portion of said backside surface on said substrate and said secondary focus ring reduces said clearance space.

18. The method as recited in claim 17, wherein said secondary focus ring reduces exposure of said backside surface.

19. The method as recited in claim 11, wherein a portion of said backside surface on said substrate is exposed and wherein said secondary focus ring reduces said exposure of said backside surface.

20. The method as recited in claim 11, wherein said secondary focus ring makes contact with said substrate and makes contact with said focus ring.